

## TIDA-01634 REV E1 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
I PCB1	1		XX####	Any	Printed Circuit Board	
C1, C11	2	10uF	885012208069	Wurth Elektronik	CAP, CERM, 10 $\mu$ F, 25 V, +/- 10%, X7R, 1206	1206
C2, C14	2	0.47uF	YFF18PW0J474M	TDK	Feedthru Capacitor, 0.47uF, 6.3V, SMD	0603
C3, C19	2	1uF	GRM55DR72E105KW01L	MuRata	CAP, CERM, 1 $\mu$ F, 250 V, +/- 10%, X7R, 2220	2220
C4, C5, C12, C16	4	0.022uF	QMK212B7223KG-T	Taiyo Yuden	CAP, CERM, 0.022 $\mu$ F, 250 V, +/- 10%, X7R, 0805	0805
C6, C8, C9, C15	4	6800pF	CGA3E2X7R2A682K080AA	TDK	CAP, CERM, 6800 pF, 100 V, +/- 10%, X7R, AEC-Q200 Grade 1, 0603	0603
C7, C10, C17, C18, C20, C21	6	0.22uF	GRM32DR72E224KW01L	MuRata	CAP, CERM, 0.22 $\mu$ F, 250 V, +/- 10%, X7R, 1210	1210
C13	1	0.1uF	GRM188R71E104KA01D	MuRata	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0603	0603
D1	1	100V	BAT46WJ,115	NXP Semiconductor	Diode, Schottky, 100 V, 0.25 A, SOD-323F	SOD-323F
H1, H2, H3, H4	4		SJ-5303 (CLEAR)	3M	Bumpon, Hemisphere, 0.44 X 0.20, Clear	Transparent Bumpon
J1	1		OSTVN02A150	On-Shore Technology	Terminal Block, 2.54mm, 2x1, Brass, TH	Terminal Block, 2.54mm, 2-pole, Brass, TH
J2, J5	2		282841-2	TE Connectivity	Terminal Block, 2x1, 5.08mm, TH	10.16x15.2x9mm
J3, J6	2		GBC02SAAN	Sullins Connector Solutions	Header, 2.54 mm, 2x1, Gold, TH	Header, 2.54 mm, 2x1, TH
J4	1		5-146278-4	TE Connectivity	Header, 100mil, 4x1, Tin, TH	Header, 4x1, 100mil, TH
L1	1	1uH	74438357010	Wurth Electronics Inc.	=description	Nonstandard SMD
Q1, Q2, Q3, Q4	4		EPC8009	Efficient Power Conversion (E	MOSFET, N-CH, 40 V, 2.7 A, SMD, 6-Leads, Body 2.05x0.85mm	
R1, R2, R4, R8, R31	5	0	ERJ-2GE0R00X	Panasonic	RES, 0, 5%, 0.063 W, 0402	0402
R3, R5, R7, R10	4	0	ERJ-1GE0R00C	Panasonic	RES, 0, 5%, 0.05 W, 0201	0201
R6, R9	2	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402
R11, R12	2	20.0k	CRCW020120K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.05 W, 0201	0201
R13, R14	2	1M	3224X-1-105E	Bourns	TRIMMER 1M OHM 0.25W SMD	3.5x5.3x4.8mm
TP1	1		5009	Keystone	Test Point, Compact, Yellow, TH	Yellow Compact Testpoint
TP2	1	Red	5005	Keystone	Test Point, Compact, Red, TH	Red Compact Testpoint
TP4, TP7	2	Black	5006	Keystone	Test Point, Compact, Black, TH	Black Compact Testpoint
TP6, TP10	2	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP13	1	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
U1	1		LMG1210RVR	Texas Instruments	Advanced eGaN FET 300V Half-bridge Drive, RVR0019A	RVR0019A
U2	1		SN74LVC2G17DBVR	Texas Instruments	Dual Schmitt Trigger Buffer, DBV0006A (SOT-6)	DBV0006A

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